



For All Sputtering Process Product **ARC Coating**

It is important to form a coating with a surface structure which can prevent abnormal delamination by increasing the deposition strength of sputtering particles (coating material) dispersed on the inner wall of the chamber during the PVD process. By suppressing abnormal delamination of deposited particles from the surface structure formed on the inner wall of the chamber, it is possible to prevent contamination and defects on the coating which are deposited on one side of the substrate during sputtering.

Mechanism

ARC Coating is,

a technology that uses two metal wires as electrodes to apply different voltages, and the wires are melted at the end point where the two wires meet by ARC generation and compressed air is sprayed at the same time to fuse the molten metal to the substrate to form the coating.

Benefit

ARC Coating forms roughness on the inner wall of the sputtering PVD chamber to prevent the sputtering deposits from peeling off the chamber wall, thereby extending the life cycle of the parts. In addition, since ARC coating sprays the melted wire, melted by ARC, with compressed air, various types of roughness can be formed by changing the spraying parameters. So, **CINOS can provide metal coatings with a variety of roughness such as 600, 900, 1200 μinch, etc.**

Application

For
Semiconductor
Sputtering Parts

